NEAR CHIP SIZE SEMICONDUCTOR PACKAGE

ABSTRACT

A semiconductor package that can fit semiconductor chips of various sizes without having to change the footprint of the carrier package. One aspect of the semiconductor package comprises a leadframe, a semiconductor chip attached to the leadframe, electrical connectors electrically connecting the semiconductor to the leadframe, and a sealing material. The leadframe has a plurality of leads, with each one of the plurality of leads having an upper side, a lower exposed side, and a laterally exposed side. The upper side of each one of the plurality of leads define a generally co-planar surface. Further, after sealing material encapsulates the components of the semiconductor package in a spacial relationship, the lower exposed side and the lateral exposed side of the plurality of leads are exposed to the outside surface of the semiconductor package.

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